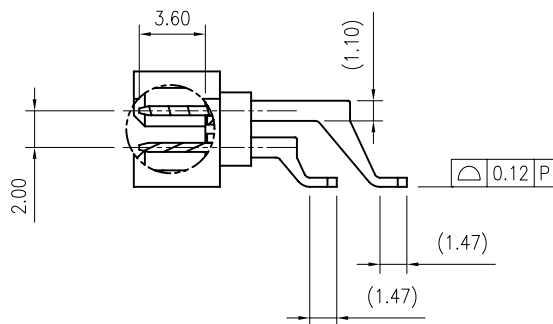
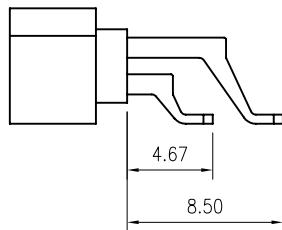


RECOMMEND PCB PATTERN



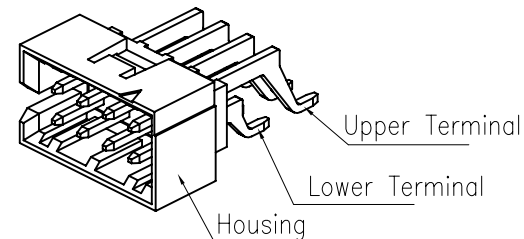
NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
 - 1.2 CONTACT: COPPER ALLOY
2. FINISH:
 - 2.1 CONTACT: 50~100u" NICKEL UNDERPLATING OVERALL. 80u"MIN MATTE TIN OVER THE NICKEL
 - 2.2 SOLDER: 50~100u" NICKEL UNDERPLATING OVERALL. 80u"MIN MATTE TIN OVER THE NICKEL
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO SPEC-51352-xxxxx-xxx
5. PACKAGE PLS. REFER TO 51353-xxxxx-xx-TRP
6. OPERATING INSTRUCTIONS:THE ASSEMBLY LINE CAN NOT BE LEFT OR RIGHT OR UP AND DOWN TILT PULL OUT
7. PART NUMBER

51353-XXX X X -XXX
 CKT _____ PLATING _____
 001 _____
 N:MATTE TIN

PACKING

- 0:TAPE & REEL
- 4:Tape & Reel with Mylar



CKT.	DIM A	DIM B	DIM C	DIM D
008	6.00	8.85	10.65	9.00

一般公差 TOLERANCES X. ±0.5 XX ±0.15 X ±0.25 XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronics Co.,Ltd.	
檢驗尺寸標示 SYMBOLS ① ② INDICATE CLASSIFICATION DIMENSION ③ MARK IS CRITICAL DIM. ④ MARK IS MAJOR DIM.	品名 (TITLE) 2.0 mm Pitch WT B Wafer Conn SMT D/R R/A TYPE 圖號 (DWG NO.) 51353-XXXXX-XXX	製圖 (DR) 17/11/15 Liang,lin ji 審核 (CHKD) Lu, jing quan 核准 (APPD) Hsieh, fu yu	張數 (SHEET) 1 OF 1 SIZE A4 REV 0
表面處理 (FINISH)	比例 (SCALE) 4:1	單位 (UNITS) mm	